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NOTES:

I.) MATERIAL:

HOUSING: LCP CONTACT: COPPER ALLOY PLATING (CONTACT): Au OVER Ni. UL RATING: 94 V-O SOLDERBALL: (SEE TABLE) EUTECTIC SnPb OR LEAD FREE 95.5 Sn/4Ag/0.5Cu.

(2.) SOLDER BALLS WILL NOT BE PERFECT SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.

(3.) MATED HEIGHT EFFECTED BY CUSTOMERS' PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTE.

CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T} ARE SINGLE BEAM CONTACTS, USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])

CONTACTS IN ROWS B.D.F.H.L.N.Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.

SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE DOC. NO. GS-20-016.

FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.

THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. PRODUCT MEETING THIS DIRECTIVE IS INDENTIFIED IN THE CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSTION.

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Pro/E File - REV C - 2009-06-09

spec ref dr Louis Ng 2010/11/01 projection scale size mm A 4 tolerance std eng Nickor Zuo 2011/05/30 11:10 TOLERANCES UNLESS ELX-DG-003943-1 Alex Cao 2011/06/24 ASME YI4.5 chr ecn no OTHERWISE SPECIFIED Pei-Ming Zheng 2011/06/27 GIG-Array rel level product family appr Released ± 0.30 0.X 0 rev GIG-Array (SELECT LOAD) ± 0.10 10082973 surface 0.XX linear D × 0 В ± 0.05 RECP. ASSY 0.XXX I5mm $\pm 2^{\circ}$ 0° **|www.fci.com**|cat.no. Product - Customer Drw sheet 5 of 5 angular

STATUS:Released

PDS: Rev:B

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